3.3 V / 5 V ECL JK Flip-Flop

Description

The MC100EP35 is a higher speed/low voltage version of the EL35 JK flip-flop. The J/K data enters the master portion of the flip-flop when the clock is LOW and is transferred to the slave, and thus the outputs, upon a positive transition of the clock. The reset pin is asynchronous and is activated with a logic HIGH.

The 100 Series contains temperature compensation.

Features

- 410 ps Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range:
 - $V_{CC} = 3.0 \text{ V}$ to 5.5 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range:
 - $V_{CC} = 0 \text{ V}$ with $V_{EE} = -3.0 \text{ V}$ to -5.5 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



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SOIC-8 NB **D SUFFIX CASE** 751-07

TSSOP-8 DT SUFFIX CASE 948R-02

MARKING DIAGRAMS*





= MC100 A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

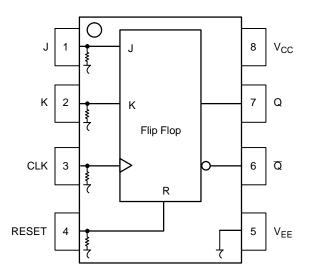


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

PIN	FUNCTION
CLK*	ECL Clock Inputs
J*, K*	ECL Signal Inputs
RESET*	ECL Asynchronous Reset
Q, Q	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply

^{*} Pins will default LOW when left open.

Table 2. TRUTH TABLE

L L L Z Qn L H L Z L	J	K	RESET	CLK	Qn+1
H L Z H Z Qn	L L H	L H H	L L L	-	L H

Z = LOW to HIGH Transition

Table 3. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	N/A
ESD Protection Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
SOIC-8 NB TSSOP-8	Level 1 Level 3
Flammability Rating Oxygen Index: 28 to 34	UL-94 V-0 @ 0.125 in
Transistor Count	77 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

^{1.} For additional information, see Application Note <u>AND8003/D</u>.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$ V_I \leq V_{CC} \\ V_I \geq V_{EE} $	6 -6	V
l _{out}	Output Current	Continuous Surge		50 100	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB	190 130	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8	185 140	°C/W
θЈС	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
T _{sol}	Wave Solder (Pb-Free)	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 5. 100EP DC CHARACTERISTICS, PECL (V_{CC} = 3.3 V, V_{EE} = 0 V (Note 1))

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V _{OH}	Output HIGH Voltage (Note 2)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Output LOW Voltage (Note 2)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V $_{CC}$. V $_{EE}$ can vary +0.3 V to -2.2 V.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.

Table 6. 100EP DC CHARACTERISTICS, PECL ($V_{CC} = 5.0 \text{ V}$, $V_{EE} = 0 \text{ V}$ (Note 1))

		-40°C		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V _{OH}	Output HIGH Voltage (Note 2)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V _{OL}	Output LOW Voltage (Note 2)	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	3775		4120	3775		4120	3775		4120	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3055		3375	3055		3375	3055		3375	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.
- 2. All loading with 50 Ω to V $_{CC}$ 2.0 V.

Table 7. 100EP DC CHARACTERISTICS, NECL ($V_{CC} = 0 \text{ V}$; $V_{EE} = -5.5 \text{ V}$ to -3.0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V _{OH}	Output HIGH Voltage (Note 2)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V _{OL}	Output LOW Voltage (Note 2)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V_{CC}.
- 2. All loading with 50 Ω to V_{CC} 2.0 V.

Table 8. AC CHARACTERISTICS ($V_{CC} = 0 \text{ V}$; $V_{EE} = -3.0 \text{ V}$ to -5.5 V or $V_{CC} = 3.0 \text{ V}$ to 5.5 V; $V_{EE} = 0 \text{ V}$ (Note 1))

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (See Figure 2. F _{max} /JITTER)		> 3			> 3			> 3		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential R, CLK to Q, $\overline{\mathbf{Q}}$	200	400	480	200	410	490	200	420	575	ps
t _{RR}	Reset Recovery	150	80		150	90		150	100		ps
t _S	Setup Time Hold Time	150 150	50 50		150 150	50 50		150 150	80 80		ps
t _{PW}	Minimum Pulse width RESET	550	400		550	400		550	400		ps
tJITTER	Cycle-to-Cycle Jitter (See Figure 2. F _{max} /JITTER)		0.2	< 1		0.2	< 1		0.2	< 1	ps
t _r t _f	Output Rise/Fall Times Q, \overline{Q} (20% – 80%)	70	120	170	80	130	180	100	150	200	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} – 2.0 V.

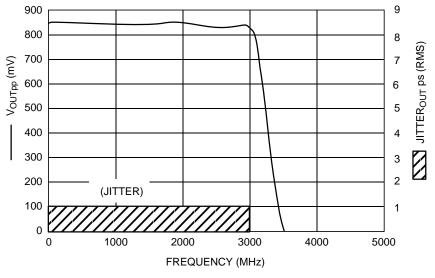


Figure 2. F_{max}/Jitter

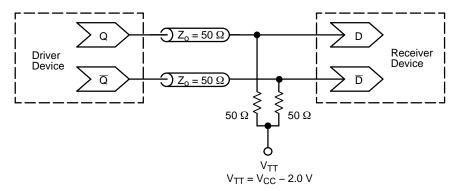


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100EP35DG	SOIC-8 NB (Pb-Free)	98 Units / Rail
MC100EP35DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EP35DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

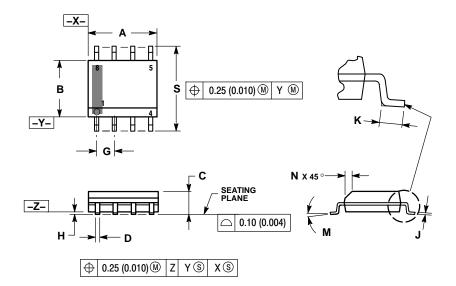
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**

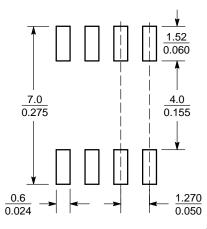


NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.
- STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES					
DIM	MIN	MAX	MIN	MAX					
Α	4.80	5.00	0.189	0.197					
В	3.80	4.00	0.150	0.157					
С	1.35	1.75	0.053	0.069					
D	0.33	0.51	0.013	0.020					
G	1.27	7 BSC	0.05	0 BSC					
Н	0.10	0.25	0.004	0.010					
J	0.19	0.25	0.007	0.010					
K	0.40	1.27	0.016	0.050					
М	0 °	0 ° 8 °		8 °					
N	0.25	0.50	0.010	0.020					
S	5.80	6.20	0.228	0.244					

SOLDERING FOOTPRINT*

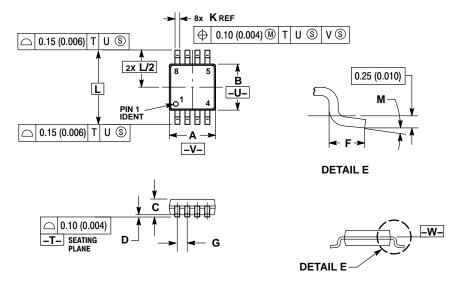


SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 CASE 948R-02 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 V14 FM 1092
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- CONTROLLING DIMENSION, MILLIMETETT.
 SI DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
- (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193		
M	0°	6 °	0°	6°	

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TC7WZ74FK,LJ(CT CD54HCT273F HMC853LC3TR HMC723LC3CTR MM74HCT574MTCX MM74HCT273WM SN74LVC74APW
SN74LVC74AD MC74HC73ADTR2G MC74HC11ADG SN74ALVTH16374GR M74HCT273B1R M74HC377RM13TR
M74HC374RM13TR M74HC175B1R M74HC174RM13TR 74ALVTH16374ZQLR 74ALVTH32374ZKER 74AUP1G74DC,125
74VHC374FT(BJ) 74VHC9273FT(BJ) NLV14013BCPG